

Appl. No. 10/803,178
Amdt. dated December 28, 2005
Reply to Office Action of October 4, 2005

Atty. Ref. 81754.0114
Customer No. 26021

Amendments to the Specification

Please replace the title with the following amended title:

~~Semiconductor Wafer, Semiconductor Device and Method for Manufacturing Same, Circuit Board and Electronic Apparatus~~ with External Terminal Joined to Concave Portion of Wiring Layer